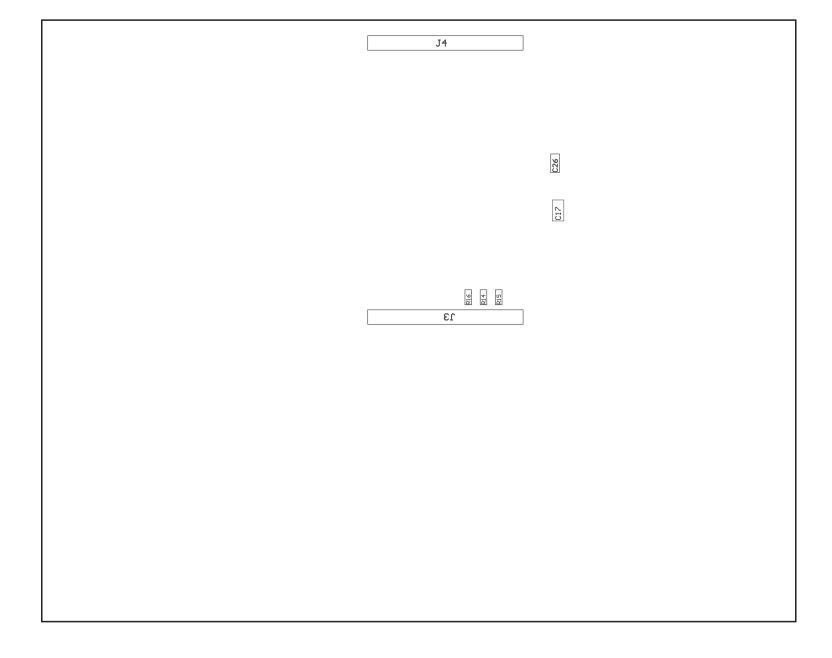


## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01330	REV: E1	SUN REU:	: Not In VersionControl
TID #: TIDA-01330				
PLOT NAME = Top Assembly Drawing	GENERATED : 2/14/2	2017 12:05:09	PM	TEXAS INSTRUMENTS



## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01330 REV: E1	SVN REV: Not In VersionControl
	TID #: TIDA-01330	
PLOT NAME = Bottom Assembly Drawing	GENERATED : 2/14/2017 12:05:11	PM TEXAS INSTRUMENTS

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